

1A, 45V Trench Schottky Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Trench Schottky technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- On-board DC/DC converter
- Automotive

MECHANICAL DATA

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	TINU	
I _F	1	Α	
V_{RRM}	45	٧	
I _{FSM}	25	Α	
T _{J MAX}	175	°C	
Package	Micro SMA		
Configuration	Single die		









Micro SMA



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER		SYMBOL	TSU1M45H	UNIT
Marking code on the device			Z1	
Repetitive peak reverse voltage		V_{RRM}	45	V
Reverse voltage, total rms value		V _{R(RMS)}	31	V
Forward current		I _F	1	Α
Surge peak forward current single half sine-wave superimposed on rated load	t = 8.3ms	1	25	Α
	t = 1.0ms	I _{FSM}	80	Α
Junction temperature		TJ	-55 to +175	°C
Storage temperature		T _{STG}	-55 to +175	°C

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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	R _{eJL}	20	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	73	°C/W
Junction-to-case thermal resistance	R _{eJC}	30	°C/W

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	I _F = 0.5A, T _J = 25°C	V _F	0.47	-	V
	$I_F = 1.0A, T_J = 25^{\circ}C$		0.52	0.60	V
	$I_F = 0.5A, T_J = 125$ °C		0.37	-	V
	$I_F = 1.0A, T_J = 125$ °C		0.43	0.55	V
Reverse current @ rated V _R ⁽²⁾	T _J = 25°C	1	-	80	μΑ
	T _J = 125°C	- I _R	-	3	mA
Junction capacitance	1MHz, $V_R = 4.0V$	CJ	156	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
TSU1M45H	Micro SMA	12,000 / Tape & Reel	

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CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

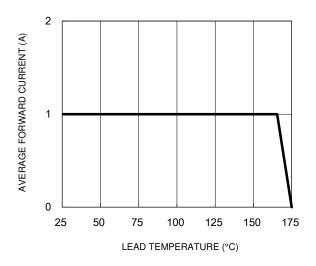


Fig.3 Typical Reverse Characteristics

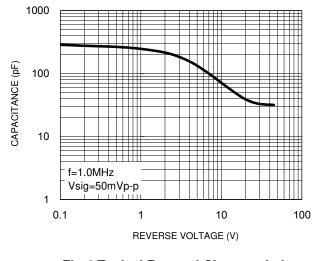
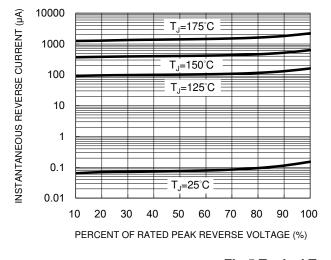


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



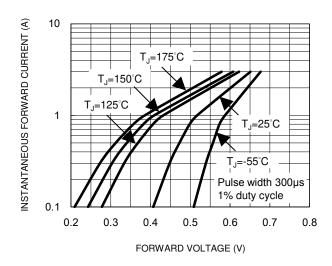
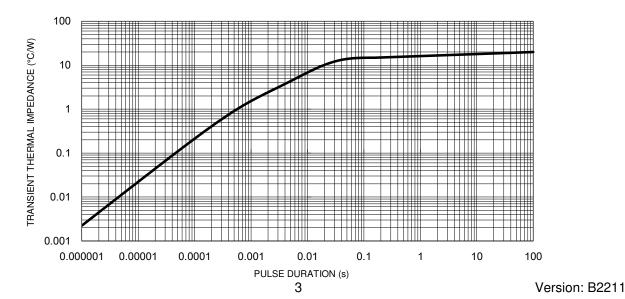


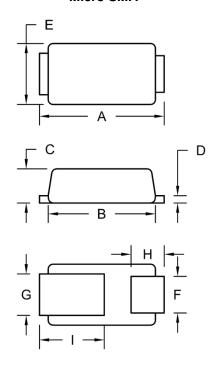
Fig.5 Typical Transient Thermal Impedance





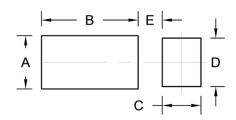
PACKAGE OUTLINE DIMENSIONS

Micro SMA



DIM.	Unit (mm)		Unit ((inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	2.30	2.70	0.091	0.106
В	2.10	2.30	0.083	0.091
С	0.63	0.73	0.025	0.029
D	0.10	0.20	0.004	0.008
E	1.15	1.35	0.045	0.053
F	0.65	0.85	0.026	0.034
G	0.75	0.95	0.030	0.037
Н	0.55	0.75	0.022	0.030
I	1.10	1.50	0.043	0.059

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.10	0.043
В	2.00	0.079
С	0.80	0.031
D	1.00	0.039
E	0.50	0.020

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

MARKING DIAGRAM



P/N = Marking Code

YW = Date Code



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